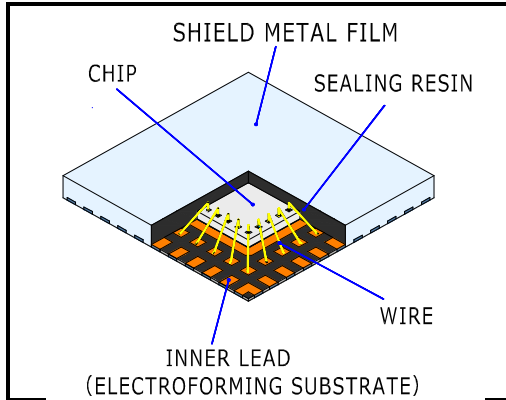


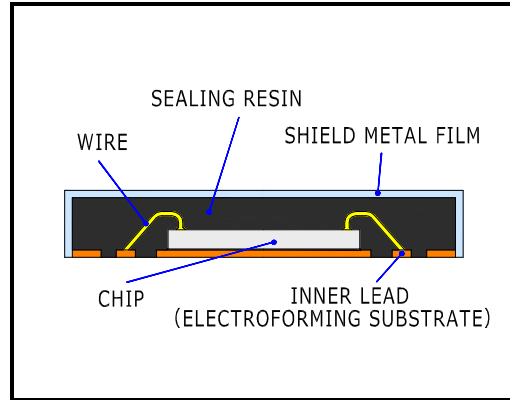
EM Noise Shielding Package

The EM Noise Suppression Technologies at the Semiconductor Package Level

Internal Structure of EM Noise Shielding Package



Cross-section of EM Noise Shielding Package

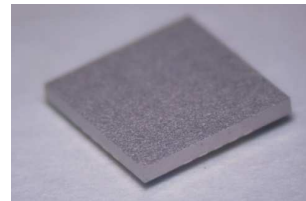


Features

- Downsizing : To allow downsizing compared to conventional metal plate shielding since there is no need to put mounting pad for metal case connecting.
- Low-profile : To provide low-profile package by using thinner electroforming substrate (acceptable from Typ 0.30mm).
- Noise Reduction : To realize higher EMI shield effect by forming shield metal film on the upper surface and four sides of package.
- Design Flexibility : To allow flexible package design because of independent terminal array pattern forming.

Application

- Smartphones, Cellular phones, Tablet Terminals, Wearable Products
- PC, DSC, Game Consoles, Household Appliances, Health Care Products
- Satellite Communication Equipments, Radio Devices (Radar, Aerials, etc.)



External View of Representative Product

Contact Us

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